	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1672	257/787.ccls.	US-PGPUB; USPAT
2	BRS	L2	1089	257/780.ccls.	US-PGPUB; USPAT
3	BRS	L3	58	L1 and BGA and (encapsulant or mold) and PCB	US-PGPUB; USPAT
4	BRS	L4	43	L2 and BGA and (encapsulant or mold) and PCB	US-PGPUB; USPAT
5	BRS	L5	17	L3 and expansion and coefficient	US-PGPUB; USPAT
6	BRS	L6	15	L4 and expansion and coefficient	US-PGPUB; USPAT
7	BRS	L7	158	L1 and (encapsulant or mold or resin) and PCB	US-PGPUB; USPAT
8	BRS	L8	48	L7 and expansion and coefficient	US-PGPUB; USPAT
9	BRS	L9	3	L8 and (mold with coefficient)	US-PGPUB; USPAT
10	BRS	L10	4	L8 and (encapsulant with coefficient)	US-PGPUB; USPAT
11	BRS	L11	9	L8 and (resin with coefficient)	US-PGPUB; USPAT

12	BRS	L12	1390	(resin or encapsulant or mold) and PCB and (coefficient ot CTE or TCE)	US-PGPUB; USPAT
13	BRS	L13	513	L12 and wire and (bump or ball)	US-PGPUB; USPAT

	Type	L #	Hits	Search Text	DBs
14	BRS	L14	88	L13 and table	US-PGPUB; USPAT
15	BRS	L15	69	L14 and (value or comparison)	US-PGPUB; USPAT
16	BRS	L16	1423	257/784.ccls.	US-PGPUB; USPAT
17	BRS	L17	1509	257/738.ccls.	US-PGPUB; USPAT
18	BRS	L18	327	257/702.ccls.	US-PGPUB; USPAT
19	BRS	L19	1790	257/787.ccls.	EPO; JPO
20	BRS	L20	453	257/784.ccls.	EPO; JPO
21	BRS	L21	98	257/780.ccls.	EPO; JPO